



HW Breakout - Feedback

AUGUST 2017

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H/W Breakout - Agenda

- Existing H/W
- H/W in development and standards
- Wishlists for new H/W
- Integration
- Peripheral H/W

Existing H/W

- ROACH2
 - Not supportable under JASPER. SKA SA to add info to wiki to ID software support.
 - About 1000 available from Digicom (lifetime buys of now obsolete components)
- SKARAB is available from Peralex
 - HMC – up to 152 ES parts available, thereafter production 2G parts
 - ADC available – Yellow Block will be available if anyone requires it to use the ADC
- SNAP is available from Digicom
 - Contact Jack H first to make sure about assembly options
- SNAP2 is available from China Academy of Science
 - Tool flow is a work in progress – expected Q4 2017
- VCU118: development board – Xilinx
 - Tool flow is a work in progress – UCB and SKA SA interested in this board
- ADC's to be listed on CASPER wiki – assume Yellow Block available if added

H/W in development and Standards

- SNAP3
 - H/W Ready October 2017
- SKARAB2
 - ~Q4 2018 (TBC)
 - Collaborators invited
- SKARAB3
 - When 7nm devices become available
- 15GSPS ADC
 - ASIAA
 - Bare PCB to be tested
- FMC+ is a standard that could be used in CASPER
- All planning to move to 100GbE - share lessons learned

Integration

- Suggested the creation of a porting workshop
- See also collaboration breakout
- Alternate between Cape Town and Berkeley initially
- SKA SA prepared to host in ~April 2018

Peripheral H/W

- Time and Frequency
 - White Rabbit
 - Freq distribution, synthesisers etc – to list these on the wiki, sharing of experience
 - Memos, sharing of papers in this field encouraged
- GPU support
 - iWarp protocol
 - ROCE
 - Infiniband to FPGA is challenging, stick to Ethernet